

IN THE CLAIMS:

This listing of claims will replace all prior versions and listings of claims in the application:

Listing of Claims:

1. (Original) A method of manufacturing a ceramic electronic device, comprising:
 - forming at least one conductive layer by applying paste mainly containing metal on at least one insulating sheet;
 - providing at least one sintered body by firing the at least one insulating sheet having the at least one conductive layer formed thereon;
 - detecting an amount of the metal contained in the at least one conductive layer of the at least one sintered body;
 - selecting a sintered body from the at least one sintered body based on the detected amount of the metal; and
 - forming an outer electrode on the selected sintered body.
2. (Original) The method of claim 1, wherein said detecting an amount of the metal contained in the at least one conductive layer of the at least one sintered body comprises:
 - causing the at least one sintered body to vibrate near a coil;
 - measuring a voltage induced on the coil; and
 - detecting the amount of the metal contained in the at least one conductive layer based on the measured induced voltage.
3. (Original) The method of claim 1, further comprising
 - forming at least one laminated body by using the at least one insulating sheet having the at least one conductive layer formed thereon,
 - wherein said providing at least one sintered body by firing the at least one insulating sheet having the at least one conductive layer formed thereon comprises providing the at least one sintered body by firing the at least one laminated body.

4. (Original) A method of manufacturing a ceramic electronic device, comprising:
forming at least one conductive layer by applying paste mainly containing metal on at least one insulating sheet;
forming at least one laminated body by using the at least one insulating sheet having the at least one conductive layer formed thereon;
detecting an amount of the metal contained in the at least one conductive layer of the at least one laminated body;
selecting a laminated body from the at least one laminated body based on the detected amount of metal;
providing a sintered body by firing the selected laminated body obtained; and
forming an outer electrode on the sintered body.

5. (Original) The method of claim 4, wherein said detecting the amount of the metal comprises:
causing the at least one laminated body to vibrate near a coil;
measuring a voltage induced on the coil; and
detecting the amount of the metal contained in the at least one conductive layer based on the measured induced voltage.

6. (Original) A method of manufacturing a ceramic electronic device, comprising:
forming at least one conductive layer by applying paste mainly containing metal on at least one insulating sheet;
detecting an amount of the metal contained in the at least one conductive layer;
selecting, based on the detected amount of the metal, an insulating sheet having a conductive layer formed thereon from the at least one insulating sheet having the at least one conductive layer formed thereon; and
providing a sintered body by firing the selected insulating sheet having the conductive layer formed thereon; and
forming an outer electrode on the sintered body.

7. (Original) The method of claim 6, wherein said detecting the amount of the metal comprises:

causing the at least the one insulating sheet having the at least one conductive layer formed thereon to vibrate near a coil;
measuring a voltage induced on the coil; and
detecting the amount of the metal contained in the at least one conductive layer based on the measured induced voltage.

8. (Original) The method of claim 6, further comprising
forming a laminated body by using the selected insulating sheet having the conductive layer formed thereon,
wherein said providing the sintered body comprises providing sintered body by firing the laminated body.

9. (Original) A method of manufacturing a ceramic electronic device, comprising:
forming at least one conductive layer by applying paste mainly containing metal on at least one insulating sheet;
providing at least one sintered body by firing the at least one insulating sheet having the at least one conductive layer formed thereon;
causing the at least one sintered body to vibrate near a coil;
measuring a voltage induced on the coil; and
selecting, based on the measured induced voltage, a sintered body from the at least one sintered body; and
forming an outer electrode on the selected sintered body.

10. (Original) The method of claim 9, further comprising
forming at least one laminated body by using the at least one insulating sheet having the at least one conductive layer formed thereon,

wherein said providing the at least one sintered body by firing the at least one insulating sheet having the at least one conductive layer formed thereon comprises providing the at least one sintered body by firing the at least one laminated body.

11. (Original) A method of manufacturing a ceramic electronic device, comprising:

forming at least one conductive layer by applying paste mainly containing metal on at least one insulating sheet;

forming at least one laminated body by using the at least one insulating sheet having the at least one conductive layer formed thereon;

causing the at least one laminated body to vibrate near a coil;

measuring a voltage induced on the coil;

selecting, based on the measured induced voltage, a laminated body from the at least one laminated body;

providing a sintered body by firing the selected laminated body; and

forming an outer electrode on the sintered body.

12. (Original) A method of manufacturing a ceramic electronic device, comprising:

forming at least one conductive layer by applying paste mainly containing metal on at least one insulating sheet;

causing the at least one insulating sheet having the at least one conductive layer formed thereon to vibrate near a coil;

measuring a voltage induced on the coil;

selecting, based on the measured induced voltage, an insulating sheet having a conductive layer formed thereon from the at least one insulating sheet having the at least one conductive layer formed thereon;

providing a sintered body by firing the selected insulating sheet having the conductive layer formed thereon; and

forming an outer electrode on the sintered body.

13. (Original) The method of claim 12, further comprising

forming a laminated by using the selected insulating sheet having the conductive layer formed thereon,

wherein said providing the sintered body comprises providing the sintered body by firing the laminated body.

14. (Currently Amended) The method of ~~any one of claims 1 to 13~~ claim 1, wherein the metal comprises nickel.

15. (Currently Amended) The method of ~~any one of claims 1 to 13~~ claim 1, wherein the insulating sheet comprises a ceramic sheet.

16. (Currently Amended) The method of ~~any one of claims 1 to 13~~ claim 1, wherein the insulating sheet comprises a base film made from insulating material.

17. (New) The method of claim 4, wherein the metal comprises nickel.

18. (New) The method of claim 4, wherein the insulating sheet comprises a ceramic sheet.

19. (New) The method of claim 4, wherein the insulating sheet comprises a base film made from insulating material.

20. (New) The method of claim 6, wherein the metal comprises nickel.

21. (New) The method of claim 6, wherein the insulating sheet comprises a ceramic sheet.

22. (New) The method of claim 6, wherein the insulating sheet comprises a base film made from insulating material.

23. (New) The method of claim 9, wherein the metal comprises nickel.

24. (New) The method of claim 9, wherein the insulating sheet comprises a ceramic sheet.
25. (New) The method of claim 9, wherein the insulating sheet comprises a base film made from insulating material.
26. (New) The method of claim 11, wherein the metal comprises nickel.
27. (New) The method of claim 11, wherein the insulating sheet comprises a ceramic sheet.
28. (New) The method of claim 11, wherein the insulating sheet comprises a base film made from insulating material.
29. (New) The method of claim 12, wherein the metal comprises nickel.
30. (New) The method of claim 12, wherein the insulating sheet comprises a ceramic sheet.
31. (New) The method of claim 12, wherein the insulating sheet comprises a base film made from insulating material.